

Global G1 eUICC SIM

Triple Cut Format



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Triple Cut Format - 2FF, 3FF, 4FF

Product overview

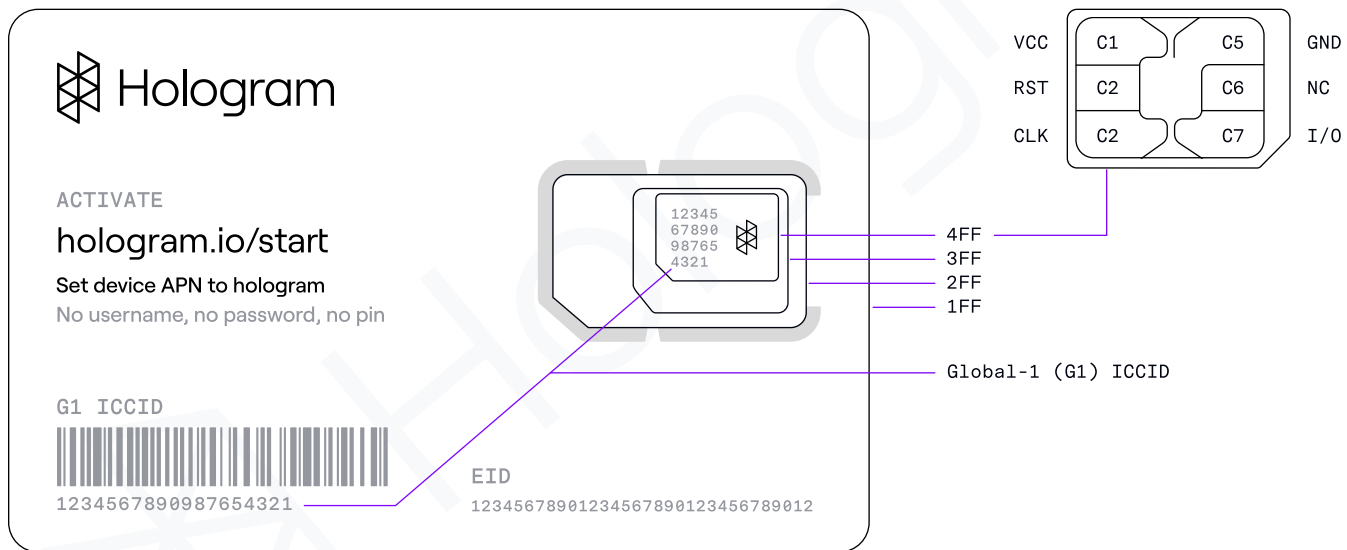
A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

Network availability

Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available. More information:

<https://www.hologram.io/pricing/coverage>

Mechanical specifications



Physical characteristics

Size

Format	Size	Dimensions (mm)
1FF	Full-Size	85.5 × 53.98 × 0.71
2FF	Mini-SIM	25 × 15 × 0.71
3FF	Micro-SIM	15 × 12 × 0.71
4FF	Nano-SIM	12.3 × 8.8 × 0.71

Pin definitions

Pin	Function	Description
C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware specifications

Chip type

Standard grade

Industrial grade

Supplier	Samsung	Samsung
Chip Code	S3FW9FG	S3FW9FJM

Hardware characteristics

Standard grade

Industrial grade

Operational Temperature	-25°C to +85°C	-40°C to 105°C
Data Retention	25 years @ 25°C	15 years @ 85°C
Write Endurance	>500K read/write cycles @ 25°C (OS enhanced)	>500K read/write cycles @ 85°C
Remaining Available Memory (NVM)	340 KB	704 KB
Memory (SRAM)	10 KB	20 KB

Electrical

Standard Grade

Industrial Grade

Operating Voltage	1.6V, 3V, and 5V	1.62V to 5.5V
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AC electrical parameters standards

ETSI 3GPP TS 102 221 Class A, B, C – UICC Terminal Interface Physical & Logical Characteristics

ETSI TS 102 671 v9.1.0 – M2M Physical and Logical Characteristics

ISO/IEC 7816-3 standard for Cards with Contacts – Electrical interface and transmission protocols

Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS		SGP:11 RSP v3.1; SGP:14 eUICC PKI v1.1; SGP:02 v3.2 ; SGP:05 eUICC PP-0089
	 TRUSTED CONNECTIVITY ALLIANCE	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.1
		Card Specification Version 2.1.1
Software		Java Card 3 Platform, Classic Edition version 3.0.4
		Release 8
Remote SIM provisioning		SGP:01 RSP v1.1 ; SGP:11 RSP v3.1 & 3.2; SGP:14 eUICC PKI v1.1 ; SAS-SM
Supplier's Declaration of Conformity		<p>Manufactured according to the following standards:</p> <ul style="list-style-type: none"> • RoHS Directive 2011/65/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 18001 • ISO 17025